PCN Number:	20230613000.1				PC	N Dat	e: June 16, 2023	
Title: Qualification of TI Clark as an alternate Assembly site for select devices								
Customer Contact: Change Management team Dept: Quality Services								
Proposed 1 st Ship Date: Sept 16, 2023			Sample Requests accepted until:			ests ntil:	July 16, 2023	
*Sample requests	s received aft	er July 16,	, 2023	3 will not be su	pport	ed.		
Change Type:								
Assembly Proc			a Sheet Wafer Bump Process number change Wafer Fab Site					
Assembly Mate							Fab Sile Fab Material	
Packing/Shippi			t Proc				afer Fab Process	
	119, 200 cm 19			etails				
Description of Ch	ange:							
Texas Instruments Incorporated is announcing the qualification of CDAT as an additional Assembly site for the devices listed below. There are no construction differences between the 2 sites.								
Reason for Chang	je:							
Supply continuity								
Anticipated impa	ct on Form, Fi	t, Functio	n, Qu	ality or Reliabil	ity (p	ositive	e / negative):	
None								
Impact on Enviro	nmental Ratin	gs						
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.								
RoHS	REACH			Green Status			IEC 62474	
🛛 No Change	🛛 No C	hange		🛛 No Change		۱ 🛛	No Change	
Changes to produ	ıct identificati	on resulti	ng fro	om this PCN:				
Assembly Site	(22L))	As	sembly Country ((23L)	try Code		Assembly City	
JCAP	JCP	JCP		CHN			Jiangyin	
Clark	QAB		PHL			Angeles City, Pampanga		
Sample product shipping label (not actual product label) TEXAS INSTRUMENTS 20: MADE IN: Malaysia 20: MSL 2 /2600(/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04) OPT: ITEM: 39 LBL: 5A (L)T0:1750 (not actual product label) (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CC0:USA (22L) AS0: MLA (23L) AC0: MYS								

Product Affected:					
AFE4420YZR	AFE49I30YZR	CSD68835F5	INA186A2IYFDR		
AFE4420YZT	AFE49I30YZT	CSD68836F5	INA186A3IYFDR		
AFE4432YCHR	CSD17484F4	CSD83325L	INA186A4IYFDR		
AFE4432YCHT	CSD17484F4T	CSD83325LT	INA186A5IYFDR		
AFE44I30YZR	CSD25484F4	CSD85302L	INA191A1IYFDR		
AFE44I30YZT	CSD25484F4T	CSD85302LT	SN1805031YZR		
AFE44S30YZR	CSD58897L	CSD87501L	SN1901046YZR		
AFE44S30YZT	CSD58898F4	CSD87501LT	TPS22913CYZVR		
AFE4900YZR	CSD58903F3	DRV2604YZFR	TPS22913CYZVT		
AFE4900YZT	CSD58905F5	INA186A1IYFDR			



TI Information Selective Disclosure

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TMP144YMTR
PC	Precon Level 1	MSL1, 260C	3/720/0
ELFR	Early Life Failure Rate, 150C	24 Hours	3/3024/0
HTOL	Life Test, 150C	300 Hours	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0
HTSL	High Temp Storage Bake, 150C	1000 Hour	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0
HBM	ESD - HBM	2000 V	3/9/0
CDM	ESD - CDM	1000 V	3/9/0
LU	Latch-up	(Per JESD78)	3/18/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass
MQ	Manufacturability (Wafer Fab)	(per mfg. Site specification)	Pass
SD	Pb Free Solderability - Dip and Look	Pb Free/Solderability	3/36/0
SD	Pb Solderability - Dip and Look	Pb/Solderability	3/36/0

QBS: Qual By Similarity
Qual Device TMP144YMTR is qualified at LEVEL1-260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free (SMT) and Green

TI Qualification ID: 20200805-135627



Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TA \$2552YFF	Qual Device: TAS2553YFF
CDM	ESD - CDM	1500 V	-	3/9/0
ED	Electrical Characterization	Per Datasheet Parameters	-	Pass
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/3000/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	-
HBM	ESD - HBM	1500 V	-	3/9/0
HBM	ESD - HBM	2000 V	-	3/9/1
HBM	ESD - HBM	2500 V	-	3/9/0
HBM	ESD - HBM	3000 V	-	3/9/0
HTOL	Life Test, 125C	1000 Hours	-	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/228/0	-
LU	Latch-up	(Per JESD78)	-	3/18/0
SBS	Bump-shear	Solder Balls	3/108/0	-
TC	Temperature Cycle, -55/125C	700 Cycles	3/231/0	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/228/0	-

- QBS: Qual By Similarity

- Qual Device TAS2553YFF is qualified at LEVEL1-260C

- Qual Device TAS2552YFF is qualified at LEVEL1-260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20141010-108724

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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